RELIABILITY REPORT

FOR

MAX5383EUT+

PLASTIC ENCAPSULATED DEVICES

October 9, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX5383EUT+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX5383/MAX5384/MAX5385 low-cost, 8-bit digital-to-analog converters (DACs) in miniature 6-pin SOT23 packages have a simple 3-wire, SPI™/QSPI™/MICROWIRE™-compatible serial interface that operates up to 10MHz. The MAX5383 has an internal +2V reference and operates from a +2.7V to +3.6V supply. The MAX5384 has an internal +4V reference and operates from a +4.5V to +5.5V supply. The MAX5385 operates over the full +2.7V to +5.5V supply range and has an internal reference equal to 0.9 x VDD. The MAX5383/MAX5384/MAX5385 require an extremely low supply current of only 150µA (typ) and provide a buffered voltage output. These devices power up at zero code and remain there until a new code is written to the DAC registers. This provides additional safety for applications that drive valves or other transducers that need to be off on power-up. The MAX5383/MAX5384/MAX5385 include a 1µA, low-power shutdown mode that features software-selectable output loads of 1k , 100k , or 1M to ground.

II. Manufacturing Information

A. Description/Function:	Low-Cost, Low-Power, 8-Bit DACs with 3-Wire Serial Interface in SOT23
B. Process:	C6Y
C. Number of Device Transistors:	2161
D. Fabrication Location:	Japan
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	July 22, 2000

III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0401-0523
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115*°C/W
K. Single Layer Theta Jc:	80°C/W

IV. Die Information

A. Dimensions:	57 X 35 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 301 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 3.57 \times 10^{-9}$

$\lambda = 3.57$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the C6Y Process results in a FIT Rate of 0.90 @ 25C and 15.55 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The DA78 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX5383EUT+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	301	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data